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(74) Agents: **OLSON, Timothy J. et al.**; Wiggin and Dana  
LLP, One Century Tower, P.O. Box 1832, New Haven, CT  
06508-1832 (US).

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(71) Applicant (for all designated States except US): **AD-  
VANCED INTERCONNECT TECHNOLOGIES  
LIMITED** [MU/MU]; c/o Valmet (Mauritius) Limited,  
608 St. James Court, St. Denis Street, Port Louis (MU).

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(72) Inventors; and

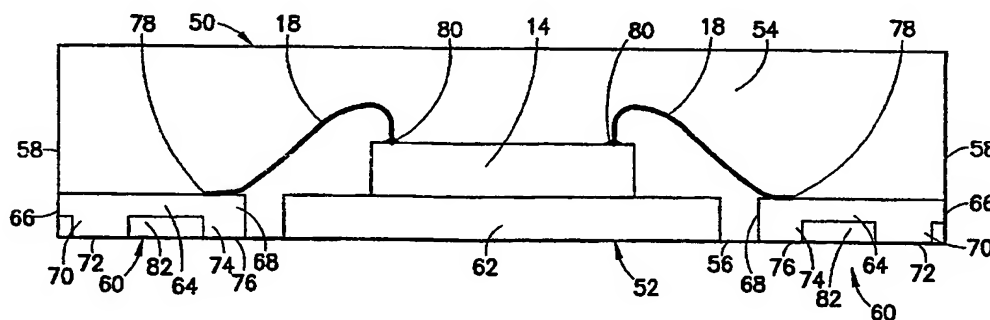
(75) Inventors/Applicants (for US only): **ISLAM, Shafidul**  
[US/US]; 3829 Lakedale Drive, Plano, TX 75025 (US).  
**LAU, Daniel, Kwok**; 395 Stonecrest Drive, San Francisco,  
CA 94132 (US). **SAN ANTONIO, Romarico Santos**  
[PH/ID]; Taman Duta Mas, Block A03-9, Batam Island  
29433 (ID). **SUBAGIO, Anang** [ID/ID]; Taman Meditera-  
nia, Block GG2/No. 39C, Batam Island 29433 (ID).  
**MCKERREGHAN, Michael Hannan** [US/US]; 3028  
Randy Lane, Farmers Branch, TX 75234 (US). **LITLIT,**  
**Edmunda, Gut-Omen** [PH/PH]; 180 Victoria Village,  
Baguio City (PH).

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(54) Title: SEMICONDUCTOR DEVICE PACKAGE AND METHOD FOR MANUFACTURING SAME



(57) Abstract: A lead frame (52, 100, 112) for a semiconductor device (die) package (50, 102, 110) is described. Each of the leads (60) in the lead frame (52, 100, 112) includes an interposer (64) having one end (66) disposed proximate the outer face (58) of the package (50, 102, 110) and another end (68) disposed proximate the die (14). Extending from opposite ends of the interposer (64) are a board connecting post (70) and a support post (74). A bond site (78) is formed on a surface of the interposer (64) opposite the support post (74). Each of the leads (60) is electrically connected to an associated input/output (I/O) pad (80) on the die (14) via wirebonding, tape bonding, or flip-chip attachment to the bond site (78). Where wirebonding is used, a wire electrically connecting the I/O pad (80) to the bond site (78) may be wedge bonded to both the I/O pad (80) and the bond site (78). The support post (74) provides support to the end (68) of the interposer (64) during the bonding and coating processes. (Figure 3)

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